OSADA et al Q67726

TERIAL FOR A HEAT DISSIPATION

STRATE FOR MOUNTING A 79.50.

SEMICONDUCTOR, METHOD OF PRODUCING....

Filed: December 13, 2001

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1 of 3



FIG. 1

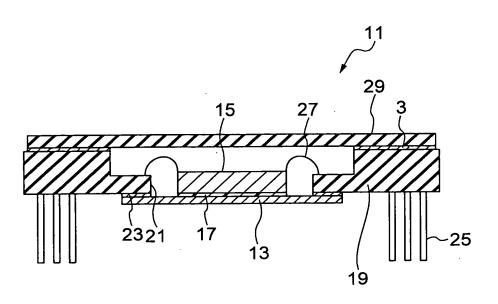
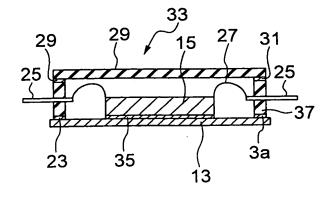
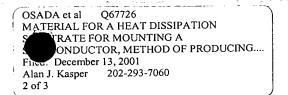


FIG. 2







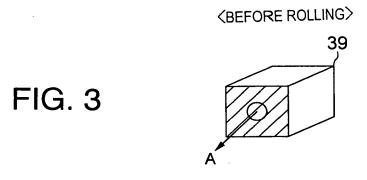
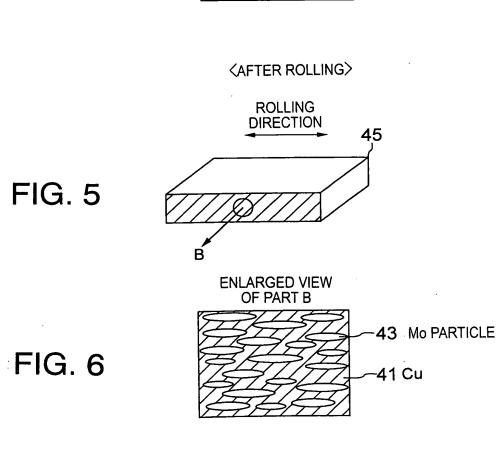


FIG. 4

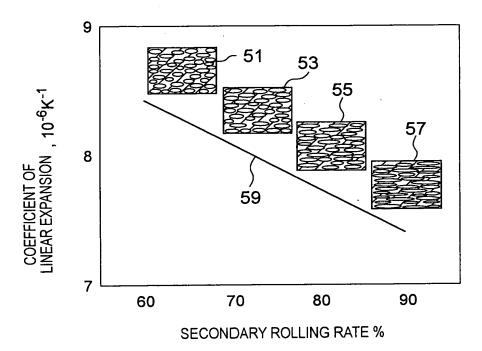
ENLARGED VIEW
OF PART A

—43 Mo PARTICLE
—41 Cu



OSADA et al Q67726
MATERIAL FOR A HEAT DISSIPATION
STRATE FOR MOUNTING A
ONDUCTOR, METHOD OF PRODUCING....
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3 of 3





RELATIONSHIP BETWEEN ROLLING RATE AND COEFFICIENT OF THERMAL EXPANSION